In the claims:

1-4 (canceled)

5. (New) A process for producing a copper clad laminate comprising,

providing an insulation layer constituent material having a first and a second side,

coating said first side with a first copper foil of a first thickness,

coating said second side with a second copper foil of a second thickness to produce an insulation layer constituent material, first copper foil and second copper foil assembly, wherein the thickness of said second foil is greater than the thickness of said first foil,

hot pressing said assembly to produce said laminate,

wherein said first copper foil is not recrystallized during said hot pressing, and

wherein said second copper foil is recystallized during said hot pressing.

6. (New) The process of claim 5, wherein the thickness of the second foil is four times or less than the thickness of the first foil.

7. (New) The process of claim 5, wherein said insulation layer constituent material is a resin.

8. (New) The process of claim 5, wherein said second copper foil contracts about

0.05% under pressing conditions of 180°C and 1hr.

9. (New) The process of claim 5, wherein said second copper foil is a S-HTE foil.

10. (New) The process of claim 5, wherein, after hot pressing, the Young's modulus of said first copper foil is 1.1 times more than the Young's modulus of said second copper foil.

11. (New) A process for producing a copper clad laminate comprising,

providing an insulation layer constituent material having a first and a second side,

coating said first side with a first copper foil of a first thickness,

coating said second side with a second copper foil of a second thickness to produce an insulation layer constituent material, first copper foil and second copper foil assembly, wherein the thickness of said second foil is greater than the thickness of said first foil,

hot pressing said assembly to produce said laminate,

wherein said first and second copper foils are recrystallized during said hot pressing, wherein said second copper foil is more recrytallized than said first copper foil.

12. (New) The process of claim 11, wherein the thickness of the second foil is four times or less than the thickness of the first foil.

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13. (New) The process of claim 11, wherein said insulation layer constituent material is a resin.

14. (New) The process of claim 11, wherein said second copper foil contracts about 0.05% under pressing conditions of 180°C and 1hr.

15. (New) The process of claim 11, wherein said second copper foil is a S-HTE foil.

16. (New) The process of claim 11, wherein, after hot pressing, the Young's modulus of said first copper foil is 1.1 times more than the Young's modulus of said second copper foil.

17. (New) A process for producing a copper clad laminate,

providing an insulation layer constituent material having a first and a second side,

coating said first side with a first copper foil of a first thickness,

coating said second side with a second copper foil of a second thickness to produce an insulation layer constituent material, first copper foil and second copper foil assembly, wherein the thickness of said second foil is greater than the thickness of said first foil,

hot pressing said assembly to produce said laminate,

wherein said first and second copper foil contract during said hot pressing,

wherein said second copper foil contracts to a larger extent than said first copper foil during said hot pressing.

18. (New) The process of claim 17, wherein the thickness of the second foil is four times or less than the thickness of the first foil.

19. (New) The process of claim 17, wherein said insulation layer constituent material is a resin.

20. (New) The process of claim 17, wherein said second copper foil contracts about 0.05% under pressing conditions of 180°C and 1hr.

21. (New) The process of claim 17, wherein said second copper foil is a S-HTE foil.

22. (New) The process of claim 17, wherein, after hot pressing, the Young's modulus of said first copper foil is 1.1 times more than the Young's modulus of said second copper foil.

23. (New) A copper clad laminate comprising

an insulation layer having a first and a second side,

a first copper foil of a first thickness attached to said first side,

a second copper foil of a second thickness attached to said second side,

wherein said second copper foil is (a) thicker, and (b) has a lower Young's modulus, than said first copper foil.

24. (New) The copper clad laminate of claim 23, the Young's modulus of said first copper foil is 1.1 times more than the Young's modulus of said second copper foil.

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25. (New) A hot pressed copper clad laminate comprising

an insulation layer constituent material having a first and a second side,

wherein said first side is coated with a first non-recrystallized copper foil, and

wherein said second side is coated with a second recrystallized copper foil, and

wherein said second copper foil is thicker than said first copper foil.

26. (New) A hot pressed copper clad laminate comprising

an insulation layer constituent material having a first and a second side,

wherein said first side is coated with a first recrystallized copper foil, and

wherein said second side is coated with a second recrystallized copper foil, and

wherein said second copper foil is

(1) thicker and (2) more recrystallized than said first copper foil.

27. (New) A hot pressed copper clad laminate according to claim 25, wherein said first copper foil is non-crystallized, and said second copper foil is crystallized.

28. (New) A hot pressed copper clad laminate according to claim 26, wherein said first and second copper foil are crystallized and wherein said second copper foil is more crystallized than said first copper foil.

29. (New) A substantially non-warped copper clad laminate comprising

an insulation layer constituent material having a first and a second side,

wherein said first side is coated with a first copper foil,

wherein said second side is coated with a second copper foil,

wherein said second copper foil is thicker than said first copper foil,

and wherein said second copper foil contracts to a larger extent than said first copper foil during a hot pressing step to produce a substantially non-warped copper clad laminate.